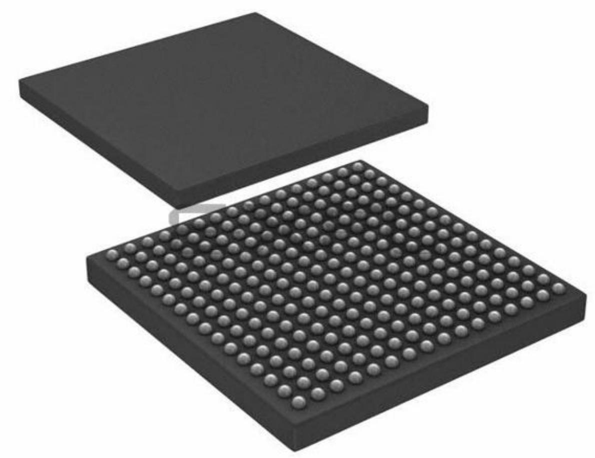

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	4224
Number of Logic Elements/Cells	-
Total RAM Bits	55296
Number of I/O	138
Number of Gates	250000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	256-LBGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax250-2fg256i

Figure 1-8 • **AX Routing Structures**

Global Resources

Each family member has three types of global signals available to the designer: HCLK, CLK, and GCLR/GPSET. There are four hardwired clocks (HCLK) per device that can directly drive the clock input of each R-cell. Each of the four routed clocks (CLK) can drive the clock, clear, preset, or enable pin of an R-cell or any input of a C-cell (Figure 1-3 on page 1-2).

Global clear (GCLR) and global preset (GPSET) drive the clear and preset inputs of each R-cell as well as each I/O Register on a chip-wide basis at power-up.

Each HCLK and CLK has an associated analog PLL (a total of eight per chip). Each embedded PLL can be used for clock delay minimization, clock delay adjustment, or clock frequency synthesis. The PLL is capable of operating with input frequencies ranging from 14 MHz to 200 MHz and can generate output frequencies between 20 MHz and 1 GHz. The clock can be either divided or multiplied by factors ranging from 1 to 64. Additionally, multiply and divide settings can be used in any combination as long as the resulting clock frequency is between 20 MHz and 1 GHz. Adjacent PLLs can be cascaded to create complex frequency combinations.

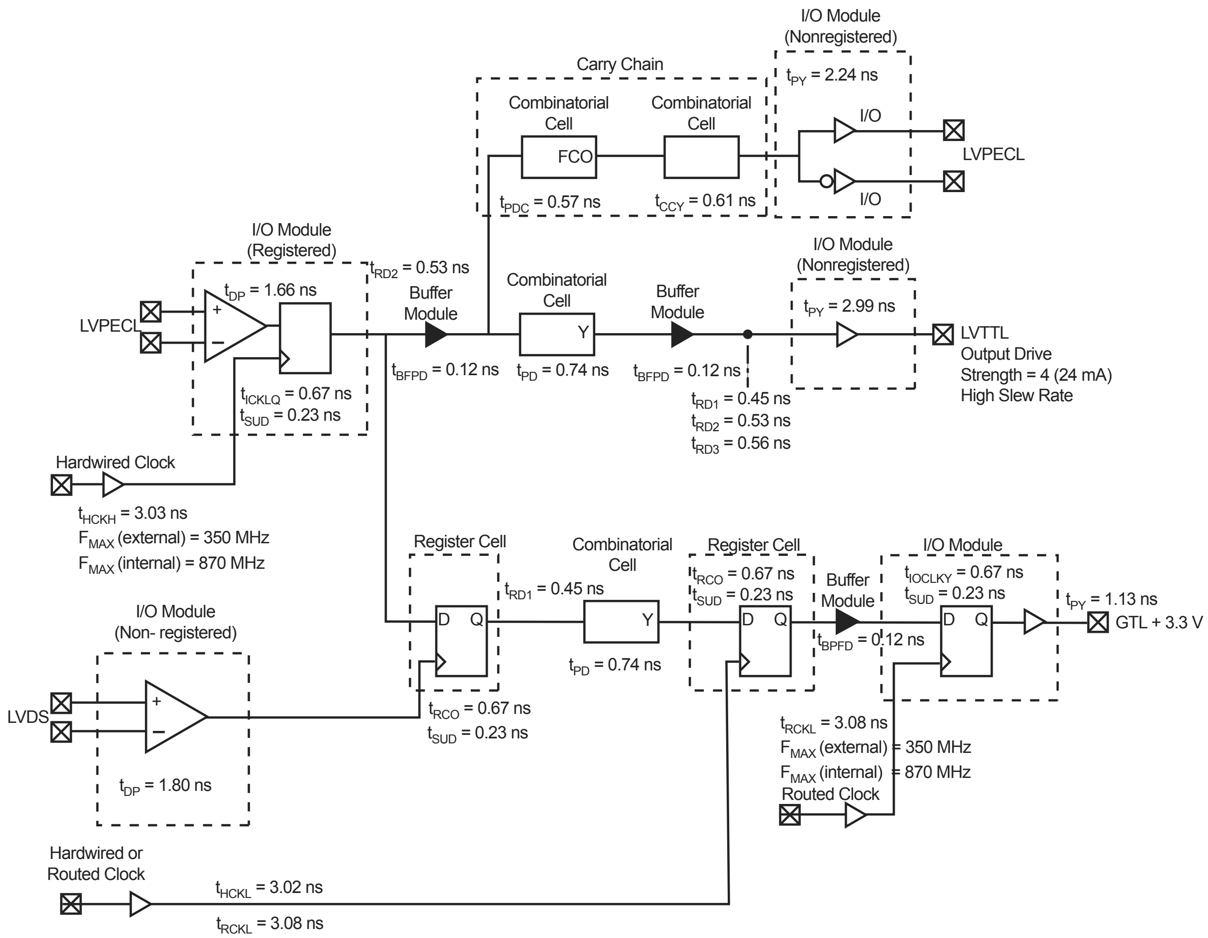
The PLL can be used to introduce either a positive or a negative clock delay of up to 3.75 ns in 250 ps increments. The reference clock required to drive the PLL can be derived from three sources: external input pad (either single-ended or differential), internal logic, or the output of an adjacent PLL.

Low Power (LP) Mode

The AX architecture was created for high-performance designs but also includes a low power mode (activated via the LP pin). When the low power mode is activated, I/O banks can be disabled (inputs disabled, outputs tristated), and PLLs can be placed in a power-down mode. All internal register states are maintained in this mode. Furthermore, individual I/O banks can be configured to opt out of the LP mode, thereby giving the designer access to critical signals while the rest of the chip is in low power mode.

The power can be further reduced by providing an external voltage source (V_{PUMP}) to the device to bypass the internal charge pump (See "Low Power Mode" on page 2-106 for more information).

Timing Model



Note: Worst case timing data for the AX1000, –2 speed grade

Figure 2-1 • **Worst Case Timing Data**

Hardwired Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) – t_{HCKL}$

$= (1.72 + 0.53 + 0.23) – 3.02 = –0.54$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{HCKL} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.02 + 0.67 + 0.45 + 2.99 = 7.13$ ns

Routed Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) – t_{RCKH}$

$= (1.72 + 0.53 + 0.23) – 3.13 = –0.65$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{RCKH} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.13 + 0.67 + 0.45 + 3.03 = 7.24$ ns

Table 2-15, Table 2-16, and Table 2-17 list all the available macro names differentiated by I/O standard, type, slew rate, and drive strength.

Table 2-15 **• Macros for Single-Ended I/O Standards**

Standard	VCCI	Macro Names
LVTTL	3.3 V	CLKBUF, HCLKBUF INBUF, OUTBUF, OUTBUF_S_8, OUTBUF_S_12, OUTBUF_S_16, OUTBUF_S_24, OUTBUF_H_8, OUTBUF_H_12, OUTBUF_H_16, OUTBUF_H_24, TRIBUF, TRIBUF_S_8, TRIBUF_S_12, TRIBUF_S_16, TRIBUF_S_24, TRIBUF_H_8, TRIBUF_H_12, TRIBUF_H_16, TRIBUF_H_24, BIBUF, BIBUF_S_8, BIBUF_S_12, BIBUF_S_16, BIBUF_S_24, BIBUF_H_8, BIBUF_H_12, BIBUF_H_16, BIBUF_H_24
3.3 V PCI	3.3 V	CLKBUF_PCI, HCLKBUF_PCI, INBUF_PCI, OUTBUF_PCI, TRIBUF_PCI, BIBUF_PCI
3.3 V PCI-X	3.3 V	CLKBUF_PCI-X, HCLKBUF_PCI-X, INBUF_PCI-X, OUTBUF_PCI-X, TRIBUF_PCI-X, BIBUF_PCI-X
LVCMOS25	2.5 V	CLKBUF_LVCMOS25, HCLKBUF_LVCMOS25, INBUF_LVCMOS25, OUTBUF_LVCMOS25, TRIBUF_LVCMOS25, BIBUF_LVCMOS25
LVCMOS18	1.8 V	CLKBUF_LVCMOS18, HCLKBUF_LVCMOS18, INBUF_LVCMOS18, OUTBUF_LVCMOS18, TRIBUF_LVCMOS18, BIBUF_LVCMOS18
LVCMOS15 (JESD8-11)	1.5 V	CLKBUF_LVCMOS15, HCLKBUF_LVCMOS15, INBUF_LVCMOS15, OUTBUF_LVCMOS15, TRIBUF_LVCMOS15, BIBUF_LVCMOS15

Table 2-16 **• I/O Macros for Differential I/O Standards**

Standard	VCCI	Macro Names
LVPECL	3.3 V	CLKBUF_LVPECL, HCLKBUF_LVPECL, INBUF_LVPECL, OUTBUF_LVPECL
LVDS	2.5 V	CLKBUF_LVDS, HCLKBUF_LVDS, INBUF_LVDS, OUTBUF_LVDS

Table 2-17 **• I/O Macros for Voltage-Referenced I/O Standards**

Standard	VCCI	VREF	Macro Names
GTL+	3.3 V	1.0 V	CLKBUF_GTP33, HCLKBUF_GTP33, INBUF_GTP33, OUTBUF_GTP33, TRIBUF_GTP33, BIBUF_GTP33
GTL+	2.5 V	1.0 V	CLKBUF_GTP25, HCLKBUF_GTP25, INBUF_GTP25, OUTBUF_GTP25, TRIBUF_GTP25, BIBUF_GTP25
SSTL2 Class I	2.5 V	1.25 V	CLKBUF_SSTL2_I, HCLKBUF_SSTL2_I, INBUF_SSTL2_I, OUTBUF_SSTL2_I, TRIBUF_SSTL2_I, BIBUF_SSTL2_I
SSTL2 Class II	2.5 V	1.25 V	CLKBUF_SSTL2_II, HCLKBUF_SSTL2_II, INBUF_SSTL2_II, OUTBUF_SSTL2_II, TRIBUF_SSTL2_II, BIBUF_SSTL2_II
SSTL3 Class I	3.3 V	1.5 V	CLKBUF_SSTL3_I, HCLKBUF_SSTL3_I, INBUF_SSTL3_I, OUTBUF_SSTL3_I, TRIBUF_SSTL3_I, BIBUF_SSTL3_I
SSTL3 Class II	3.3 V	1.5 V	CLKBUF_SSTL3_II, HCLKBUF_SSTL3_II, INBUF_SSTL3_II, OUTBUF_SSTL3_II, TRIBUF_SSTL3_II, BIBUF_SSTL3_II
HSTL Class I	1.5 V	0.75 V	CLKBUF_HSTL_I, HCLKBUF_HSTL_I, INBUF_HSTL_I, OUTBUF_HSTL_I, TRIBUF_HSTL_I, BIBUF_HSTL_I

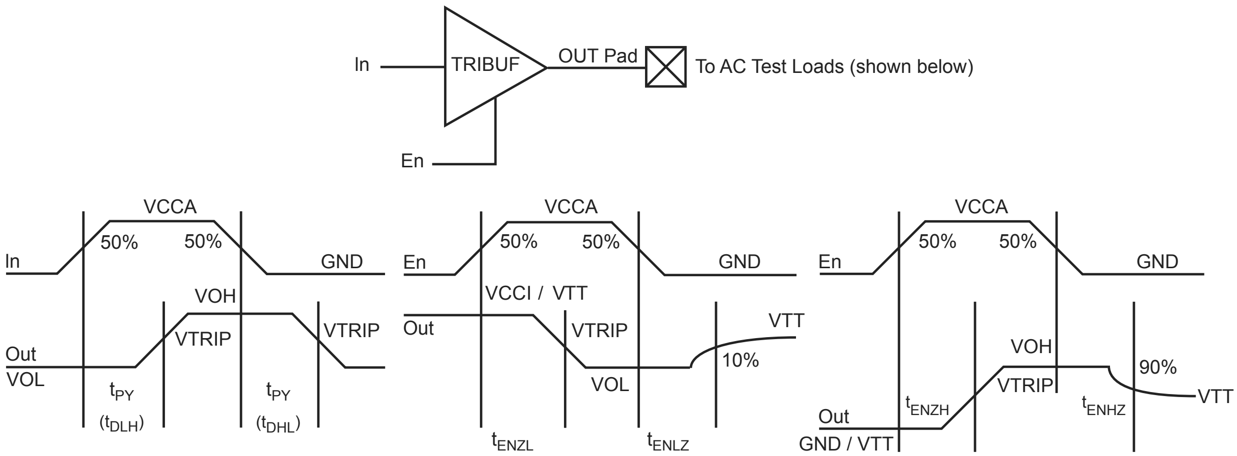


Figure 2-10 • **Output Buffer Delays**

Table 2-22 **• 3.3 V LVTTL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength = 4 (24mA) / High Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		2.99		3.41		4.01	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		2.49		2.51		2.51	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		2.59		2.95		3.46	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.91		1.93		1.93	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		3.56		4.06		4.77	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Table 2-69 • AX2000 Predicted Routing Delays
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		–2 Speed	–1 Speed	Std Speed	
Parameter	**Description**	**Typical**	**Typical**	**Typical**	**Units**
Predicted Routing Delays					
t_{DC}	DirectConnect Routing Delay, FO1	0.12	0.13	0.15	ns
t_{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t_{RD1}	Routing delay for FO1	0.50	0.56	0.66	ns
t_{RD2}	Routing delay for FO2	0.59	0.67	0.79	ns
t_{RD3}	Routing delay for FO3	0.70	0.80	0.94	ns
t_{RD4}	Routing delay for FO4	0.76	0.87	1.02	ns
t_{RD5}	Routing delay for FO5	0.98	1.11	1.31	ns
t_{RD6}	Routing delay for FO6	1.48	1.68	1.97	ns
t_{RD7}	Routing delay for FO7	1.65	1.87	2.20	ns
t_{RD8}	Routing delay for FO8	1.73	1.96	2.31	ns
t_{RD16}	Routing delay for FO16	2.58	2.92	3.44	ns
t_{RD32}	Routing delay for FO32	4.24	4.81	5.65	ns

single-ended, or voltage-referenced standard. The [H]CLKxN pad can only be used as a differential pair with [H]CLKxP.

The block marked "/i Delay Match" is a fixed delay equal to that of the i divider. The "/j Delay Match" block has the same function as its j divider counterpart.

Functional Description

Figure 2-48 on page 2-75 illustrates a block diagram of the PLL. The PLL contains two dividers, i and j, that allow frequency scaling of the clock signal:

- The i divider in the feedback path allows multiplication of the input clock by integer factors ranging from 1 to 64, and the resultant frequency is available at the output of the PLL block.
- The j divider divides the PLL output by integer factors ranging from 1 to 64, and the divided clock is available at CLK1.
- The two dividers together can implement any combination of multiplication and division up to a maximum frequency of 1 GHz on CLK1. Both the CLK1 and CLK2 outputs have a fixed 50/50 duty cycle.
- The output frequencies of the two clocks are given by the following formulas (f_{REF} is the reference clock frequency):

$$f_{CLK1} = f_{REF} * (DividerI) / (DividerJ)$$

EQ 4

$$f_{CLK2} = f_{REF} * (DividerI)$$

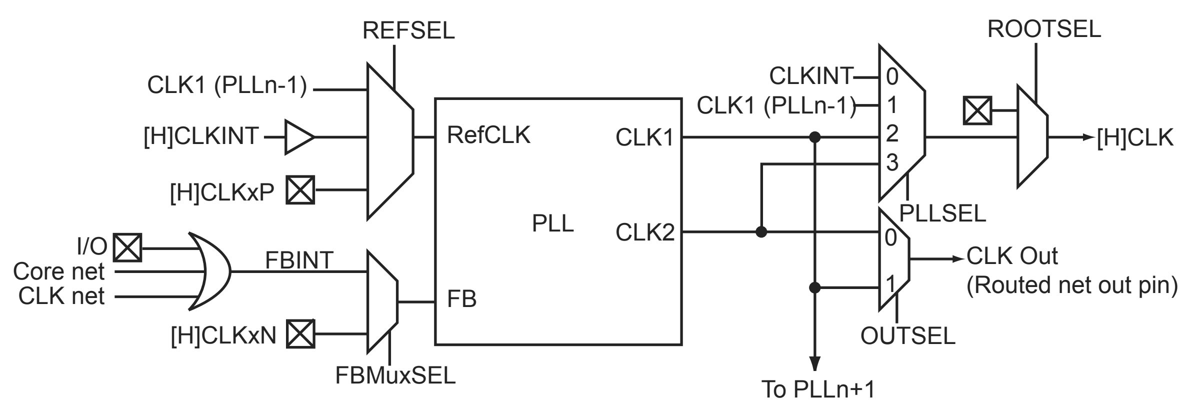
EQ 5

- CLK2 provides the PLL output directly—without division

The input and output frequency ranges are selected by LowFreq and Osc(2:0), respectively. These functions and their possible values are detailed in Table 2-80 on page 2-77.

The delay lines shown in Figure 2-48 on page 2-75 are programmable. The feedback clock path can be delayed (using the five DelayLine bits) relative to the reference clock (or vice versa) by up to 3.75 ns in increments of 250 ps. Table 2-80 on page 2-77 describes the usage of these bits. The delay increments are independent of frequency, so this results in phase changes that vary with frequency. The delay value is highly dependent on V_{CC} and the speed grade.

Figure 2-49 is a logical diagram of the various control signals to the PLL and shows how the PLL interfaces with the global and routing networks of the FPGA. Note that not all signals are user-accessible. These non-user-accessible signals are used by the place-and-route tool to control the configuration of the PLL. The user gains access to these control signals either based upon the connections built in the user's design or through the special macros (Table 2-84 on page 2-81) inserted into the design. For example, connecting the macro PLLOUT to CLK2 will control the OUTSEL signal.



Note: Not all signals are available to the user.

***Figure 2-49* • PLL Logical Interface**

Sample Implementations

Frequency Synthesis

Figure 2-53 illustrates an example where the PLL is used to multiply a 155.5 MHz external clock up to 622 MHz. Note that the same PLL schematic could use an external 350 MHz clock, which is divided down to 155 MHz by the FPGA internal logic.

Figure 2-54 illustrates the PLL using both dividers to synthesize a 133 MHz output clock from a 155 MHz input reference clock. The input frequency of 155 MHz is multiplied by 6 and divided by 7, giving a CLK1 output frequency of 132.86 MHz. When dividers are used, a given ratio can be generated in multiple ways, allowing the user to stay within the operating frequency ranges of the PLL.

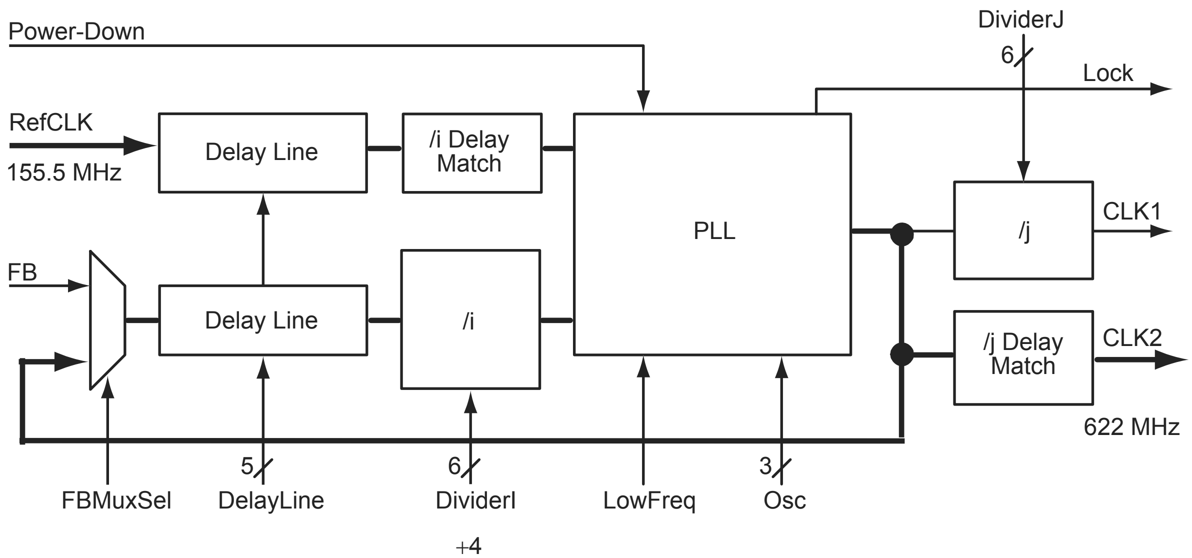


Figure 2-53 • **Using the PLL 155.5 MHz In, 622 MHz Out**

Adjustable Clock Delay

Figure 2-55 illustrates using the PLL to delay the reference clock by employing one of the adjustable delay lines. In this case, the output clock is delayed relative to the reference clock. Delaying the reference clock relative to the output clock is accomplished by using the delay line in the feedback path.

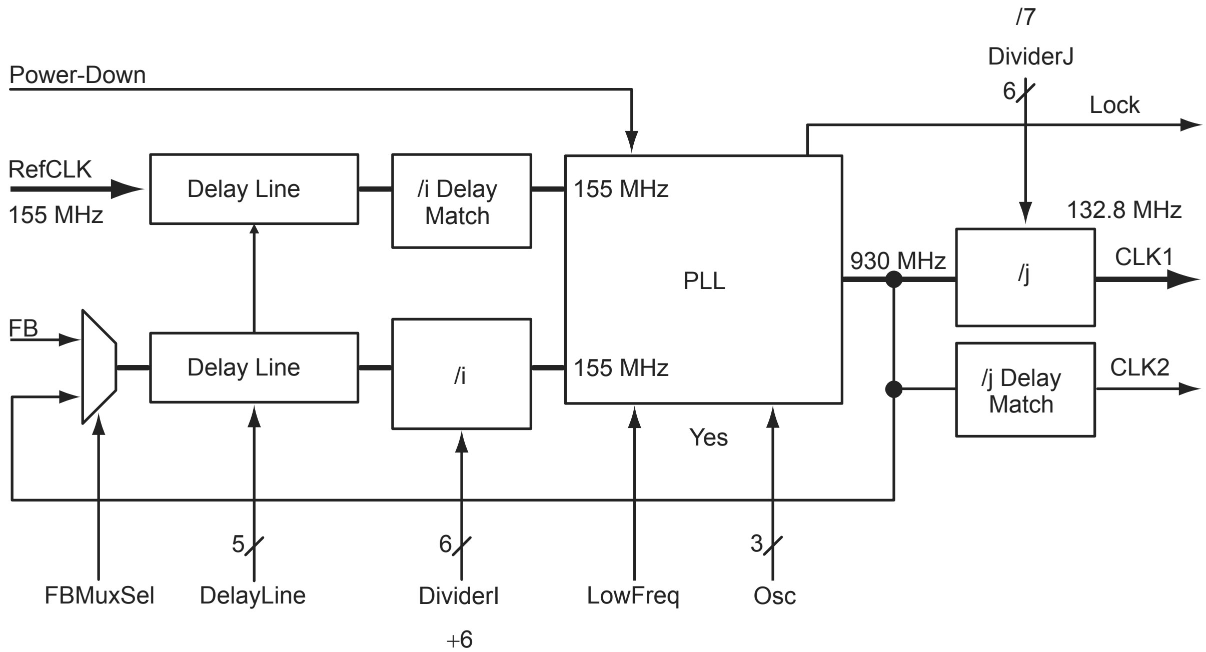


Figure 2-54 • **Using the PLL 155 MHz In, 133 MHz Out**

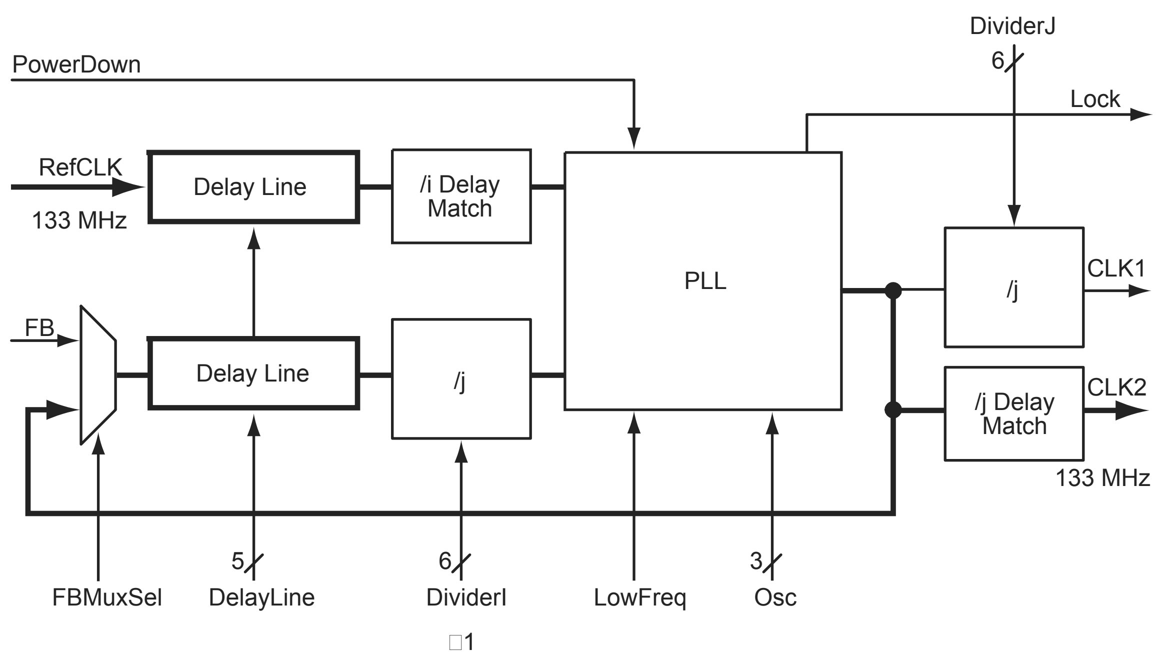


Figure 2-55 • **Using the PLL Delaying the Reference Clock**

Table 2-89 • One RAM Block
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		1.08		1.23		1.45	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.22		0.25		0.30	ns
t_{WADSU}	Write Address Setup vs. WCLK		1.08		1.23		1.45	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		1.08		1.23		1.45	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.22		0.25		0.30	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	0.88		0.88		0.88		ns
t_{WCKP}	WCLK Minimum Period	1.63		1.63		1.63		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		0.81		0.92		1.08	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		0.81		0.92		1.08	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-to-OUT (Pipelined)		1.32		1.51		1.77	ns
$t_{RCK2RD2}$	RCLK-to-OUT (Non-Pipelined)		2.16		2.46		2.90	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.77		0.77		0.77		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	0.93		0.93		0.93		ns
t_{RCKP}	RCLK Minimum Period	1.70		1.70		1.70		ns

Note: *Timing data for this single block RAM has a depth of 4,096. For all other combinations, use Microsemi's timing software.*

Glitch Elimination

An analog filter is added to each FIFO controller to guarantee glitch-free FIFO-flag logic.

Overflow and Underflow Control

The counter MSB keeps track of the difference between the read address (RA) and the write address (WA). The EMPTY flag is set when the read and write addresses are equal. To prevent underflow, the write address is double-sampled by the read clock prior to comparison with the read address (part A in Figure 2-64). To prevent overflow, the read address is double-sampled by the write clock prior to comparison to the write address (part B in Figure 2-64).

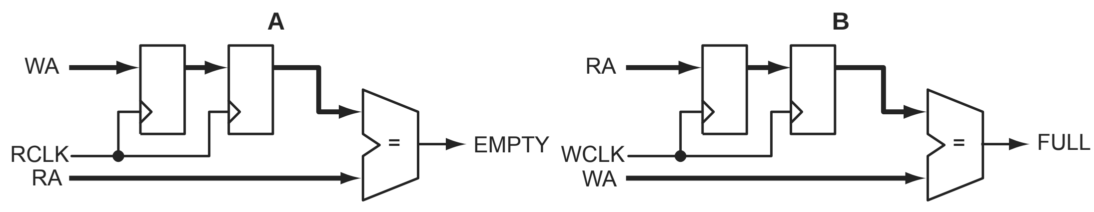


Figure 2-64 **• Overflow and Underflow Control**

FIFO Configurations

Unlike the RAM, the FIFO's write width and read width cannot be specified independently. For the FIFO, the write and read widths must be the same. The WIDTH pins are used to specify one of six allowable word widths, as shown in Table 2-96.

Table 2-96 **• FIFO Width Configurations**

WIDTH(2:0)	W x D
000	1 x 4k
001	2 x 2k
010	4 x 1k
011	9 x 512
100	18 x 256
101	36 x 128
11x	reserved

The DEPTH pins allow RAM cells to be cascaded to create larger FIFOs. The four pins allow depths of 2, 4, 8, and 16 to be specified. Table 2-86 on page 2-87 describes the FIFO depth options for various data width and memory blocks.

Interface

Figure 2-65 on page 2-99 shows a logic block diagram of the Axcelerator FIFO module.

Cascading FIFO Blocks

FIFO blocks can be cascaded to create deeper FIFO functions. When building larger FIFO blocks, if the word width can be fractured in a multi-bit FIFO, the fractured word configuration is recommended over a cascaded configuration. For example, 256x36 can be configured as two blocks of 256x18. This should be taken into account when building the FIFO blocks manually. However, when using SmartGen, the user only needs to specify the depth and width of the necessary FIFO blocks. SmartGen automatically configures these blocks to optimize performance.

TDO

TDO is normally tristated, and it is active only when the TAP controller is in the "Shift_DR" state or "Shift_IR" state. The least significant bit of the selected register (i.e. IR or DR) is clocked out to TDO first by the falling edge of TCK.

TAP Controller

The TAP Controller is compliant with the IEEE Standard 1149.1. It is a state machine of 16 states that controls the Instruction Register (IR) and the Data Registers (such as BSR, IDCODE, USRCODE, BYPASS, etc.). The TAP Controller steps into one of the states depending on the sequence of TMS at the rising edges of TCK.

Instruction Register (IR)

The IR has five bits (IR4 to IR0). At the TRST state, IR is reset to IDCODE. Each time when IR is selected, it goes through "select IR-Scan," "Capture-IR," "Shift-IR," all the way through "Update-IR." When there is no test error, the first five data bits coming out of TDO during the "Shift-IR" will be "10111". If a test error occurs, the last three bits will contain one to three zeroes corresponding to negatively asserted signals: "TDO_ERRORB," "PROBA_ERRORB," and "PROBB_ERRORB." The error(s) will be erased when the TAP is at the "Update-IR" or the TRST state. When in user mode start-up sequence, if the micro-probe has not been used, the "PROBA_ERRORB" is used as a "Power-up done successfully" flag.

Data Registers (DRs)

Data registers are distributed throughout the chip. They store testing/programming vectors. The MSB of a data register is connected to TDI, while the LSB is connected to TDO. There are different types of data registers. Descriptions of the main registers are as follow:

1. IDCODE:

   The IDCODE is a 20-bit hard coded JTAG Silicon Signature. It is a hardwired device ID code, which contains the Microsemi identity, part number, and version number in a specific JTAG format.

2. USERCODE:

   The USERCODE is a 33-bit programmable register. However, only 20 bits are allocated to use as JTAG Silicon Signature. It is a supplementary identity code for the user to program information to distinguish different programmed parts. USERCODE fuses will read out as "zeroes" when not programmed, so only the "1" bits need to be programmed.

3. Boundary-Scan Register (BSR):

   Each I/O contains three Boundary-Scan Cells. Each cell has a shift register bit, a latch, and two MUXes. The boundary-scan cells are used for the Output-enable (E), Output (O), and Input (I) registers. The bit order of the boundary-scan cells for each of them is E-O-I. The boundary-scan cells are then chained serially to form the Boundary-Scan Register (BSR). The length of the BSR is the number of I/Os in the die multiplied by three.

4. Bypass Register (BYR):

   This is the "1-bit" register. It is used to shorten the TDI-TDO serial chain in board-level testing to only one bit per device not being tested. It is also selected for all "reserved" or unused instructions.

Probing

Internal activities of the JTAG interface can be observed via the Silicon Explorer II probes: "PRA," "PRB," "PRC," and "PRD."

Special Fuses

Security

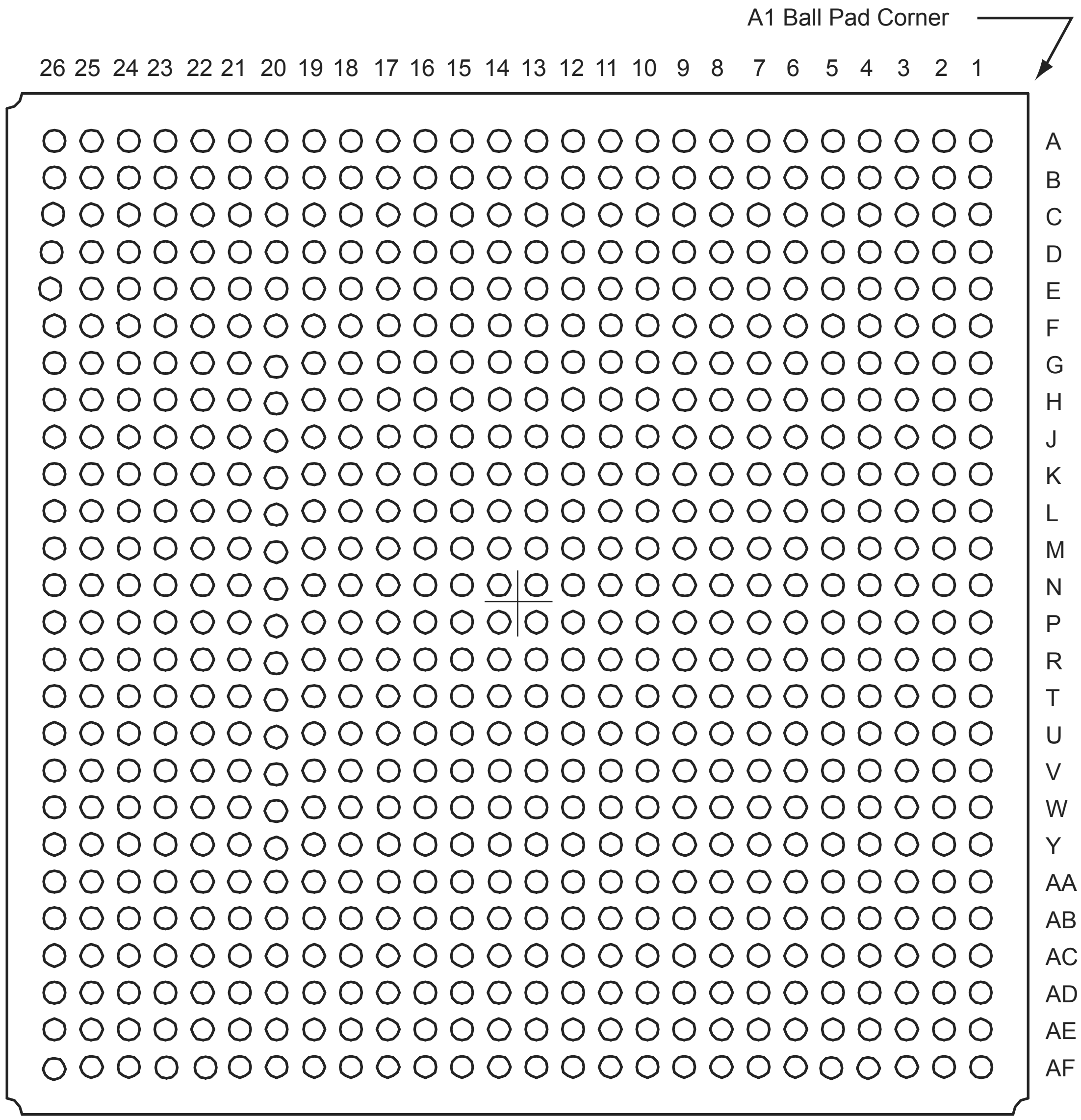
Microsemi antifuse FPGAs, with FuseLock technology, offer the highest level of design security available in a programmable logic device. Since antifuse FPGAs are live-at power-up, there is no bitstream that can be intercepted, and no bitstream or programming data is ever downloaded to the device during power-up, thus protecting against device cloning. In addition, special security fuses are hidden

BG729	
AX1000 Function	**Pin Number**
IO109NB3F10	V24
IO109PB3F10	V25
IO110NB3F10	T20
IO110PB3F10	T21
IO111NB3F10	W26
IO111PB3F10	W27
IO112NB3F10	U22
IO112PB3F10	U23
IO113NB3F10	Y26
IO113PB3F10	Y27
IO114NB3F10	U20
IO114PB3F10	U21
IO115NB3F10	W24
IO115PB3F10	W25
IO116NB3F10	V22
IO116PB3F10	V23
IO117NB3F10	Y24
IO117PB3F10	Y25
IO118NB3F11	V20
IO118PB3F11	V21
IO119NB3F11	AA26
IO119PB3F11	AA27
IO120NB3F11	W22
IO120PB3F11	W23
IO121NB3F11	AA24
IO121PB3F11	AA25
IO122NB3F11	W20
IO122PB3F11	W21
IO123NB3F11	AB26
IO123PB3F11	AB27
IO124NB3F11	Y22
IO124PB3F11	Y23
IO125NB3F11	AB24
IO125PB3F11	AB25
IO126NB3F11	AA22
IO126PB3F11	AA23
IO127NB3F11	AC26

BG729	
AX1000 Function	**Pin Number**
IO127PB3F11	AC27
IO128NB3F11	Y20
IO128PB3F11	W19
Bank 4	
IO129NB4F12	AA20
IO129PB4F12	Y21
IO130NB4F12	AB22
IO130PB4F12	AB23
IO131NB4F12	AC22
IO131PB4F12	AC23
IO132NB4F12	AD23
IO132PB4F12	AD24
IO133NB4F12	AF23
IO133PB4F12	AE23
IO134NB4F12	AC21
IO134PB4F12	AB21
IO135NB4F12	AC20
IO135PB4F12	AB20
IO136NB4F12	AD21
IO136PB4F12	AD22
IO137NB4F12	Y19
IO137PB4F12	AA19
IO138NB4F12	AE21
IO138PB4F12	AE22
IO139NB4F13	AF21
IO139PB4F13	AF22
IO140NB4F13	AG22
IO140PB4F13	AG23
IO141NB4F13	Y18
IO141PB4F13	AA18
IO142NB4F13	AE20
IO142PB4F13	AD20
IO143NB4F13	AG20
IO143PB4F13	AG21
IO144NB4F13	AC19
IO144PB4F13	AB19
IO145NB4F13	AD18

BG729	
AX1000 Function	**Pin Number**
IO145PB4F13	AD19
IO146NB4F13	AC18
IO146PB4F13	AB18
IO147NB4F13	Y17
IO147PB4F13	AA17
IO148NB4F13	AF19
IO148PB4F13	AF20
IO149NB4F13	AC17
IO149PB4F13	AB17
IO150NB4F13	AE18
IO150PB4F13	AE19
IO151NB4F13	AA16
IO151PB4F13	Y16
IO152NB4F14	AG18
IO152PB4F14	AG19
IO153NB4F14	AC16
IO153PB4F14	AB16
IO154NB4F14	AF17
IO154PB4F14	AF18
IO155NB4F14	AB15
IO155PB4F14	AC15
IO156NB4F14	AE16
IO156PB4F14	AE17
IO157NB4F14	Y15
IO157PB4F14	AA15
IO158NB4F14	AG16
IO158PB4F14	AG17
IO159NB4F14/CLKEN	AF15
IO159PB4F14/CLKEP	AF16
IO160NB4F14/CLKFN	AD14
IO160PB4F14/CLKFP	AD15
Bank 5	
IO161NB5F15/CLKGN	AE14
IO161PB5F15/CLKGP	AE15
IO162NB5F15/CLKHN	AC13
IO162PB5F15/CLKHP	AD13
IO163NB5F15	Y14

FG676



Note

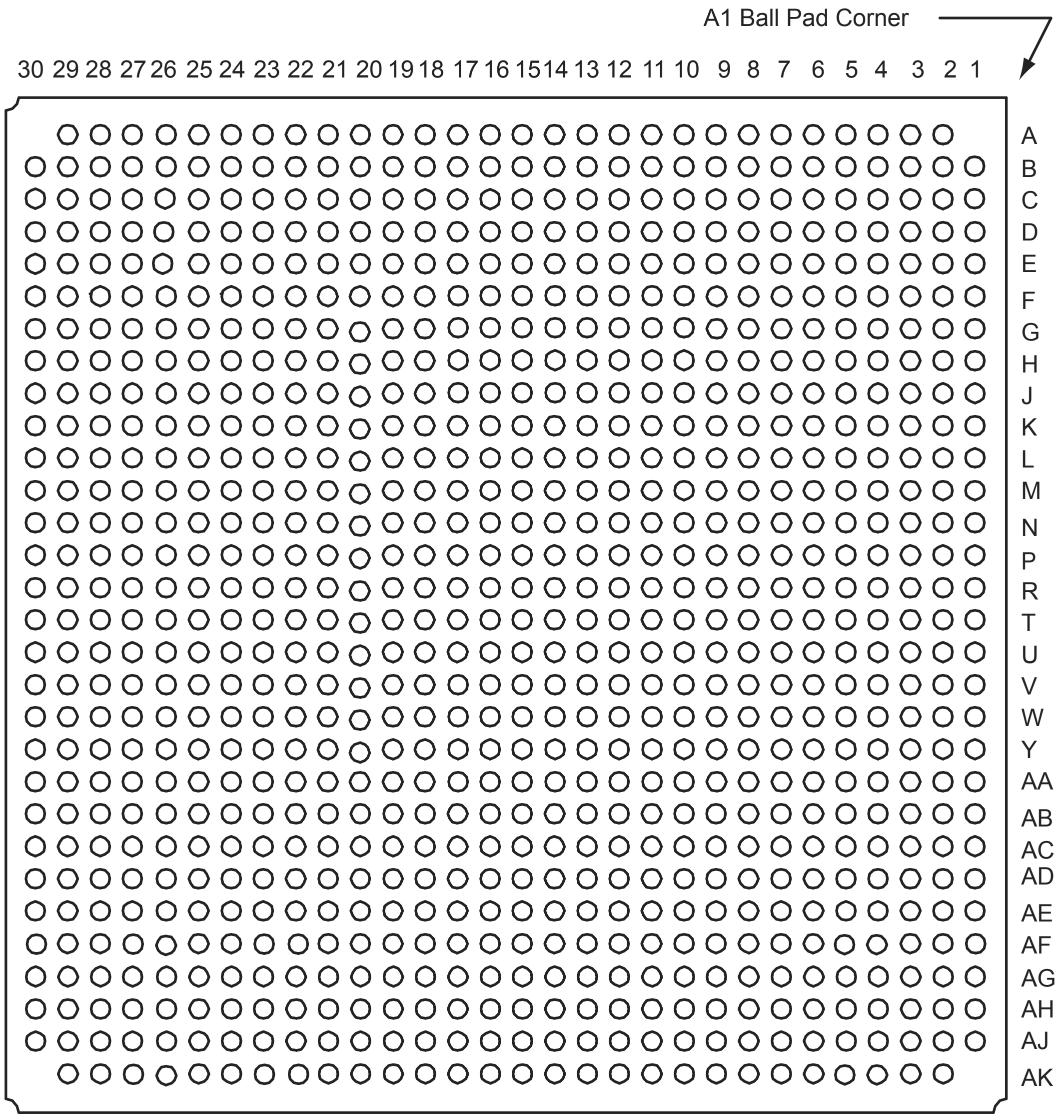
For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG676	
AX1000 Function	**Pin Number**
IO129PB4F12	AA21
IO131NB4F12	AD22
IO131PB4F12	AD23
IO132NB4F12	AE23
IO132PB4F12	AE24
IO133NB4F12	AB20
IO133PB4F12	AA20
IO134NB4F12	AC21
IO134PB4F12	AC22
IO135NB4F12	AF22
IO135PB4F12	AF23
IO137NB4F12	AB19
IO137PB4F12	AA19
IO139NB4F13	AC19
IO139PB4F13	AC20
IO140NB4F13	AE21
IO140PB4F13	AE22
IO141NB4F13	AD20
IO141PB4F13	AD21
IO143NB4F13	AB17
IO143PB4F13	AB18
IO144NB4F13	AE19
IO144PB4F13	AE20
IO145NB4F13	AC17
IO145PB4F13	AC18
IO146NB4F13	AD18
IO146PB4F13	AD19
IO147NB4F13	AA17
IO147PB4F13	AA18
IO148NB4F13	AF20
IO148PB4F13	AF21
IO149NB4F13	AA16
IO149PB4F13	Y16
IO151NB4F13	AC16
IO151PB4F13	AB16
IO153NB4F14	AE17

FG676	
AX1000 Function	**Pin Number**
IO153PB4F14	AE18
IO154NB4F14	AF17
IO154PB4F14	AF18
IO155NB4F14	AA15
IO155PB4F14	Y15
IO157NB4F14	AC15
IO157PB4F14	AB15
IO159NB4F14/CLKEN	AE16
IO159PB4F14/CLKEP	AF16
IO160NB4F14/CLKFN	AE14
IO160PB4F14/CLKFP	AE15
Bank 5	
IO161NB5F15/CLKGN	AE12
IO161PB5F15/CLKGP	AE13
IO162NB5F15/CLKHN	AE11
IO162PB5F15/CLKHP	AF11
IO163NB5F15	AC12
IO163PB5F15	AB12
IO165NB5F15	Y12
IO165PB5F15	AA13
IO167NB5F15	Y11
IO167PB5F15	AA12
IO168NB5F15	AF9
IO168PB5F15	AF10
IO169NB5F15	AB11
IO169PB5F15	AA11
IO171NB5F16	AE9
IO171PB5F16	AE10
IO173NB5F16	AC10
IO173PB5F16	AC11
IO174NB5F16	AE7
IO174PB5F16	AE8
IO175NB5F16	AC9
IO175PB5F16	AD9
IO176NB5F16	AF6
IO176PB5F16	AF7

FG676	
AX1000 Function	**Pin Number**
IO177NB5F16	AA10
IO177PB5F16	AB10
IO179NB5F16	AD7
IO179PB5F16	AD8
IO180NB5F16	AC7
IO180PB5F16	AC8
IO181NB5F17	AA9
IO181PB5F17	AB9
IO183NB5F17	AD6
IO183PB5F17	AE6
IO184NB5F17	AE5
IO184PB5F17	AF5
IO185NB5F17	AA8
IO185PB5F17	AB8
IO187NB5F17	AC5
IO187PB5F17	AC6
IO188NB5F17	AD4
IO188PB5F17	AD5
IO189NB5F17	AB6
IO189PB5F17	AB7
IO190NB5F17	AF4
IO190PB5F17	AE4
IO191NB5F17	AE3
IO191PB5F17	AF3
IO192NB5F17	AA6
IO192PB5F17	AA7
Bank 6	
IO193NB6F18	Y5
IO193PB6F18	AA5
IO194NB6F18	AB3
IO194PB6F18	AC3
IO195NB6F18	Y4
IO195PB6F18	AA4
IO196NB6F18	AC2
IO196PB6F18	AD2
IO197NB6F18	W6

FG896



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG896	
AX2000 Function	Pin Number
GND	W19
GND	Y11
GND	Y20
GND/LP	E4
PRA	G15
PRB	D16
PRC	AB16
PRD	AF16
TCK	G7
TDI	D5
TDO	J8
TMS	F6
TRST	C4
VCCA	AD6
VCCA	AH26
VCCA	E28
VCCA	E3
VCCA	L12
VCCA	L13
VCCA	L14
VCCA	L15
VCCA	L16
VCCA	L17
VCCA	L18
VCCA	L19
VCCA	M11
VCCA	M20
VCCA	N11
VCCA	N20
VCCA	P11
VCCA	P20
VCCA	R11
VCCA	R20
VCCA	T11
VCCA	T20

FG896	
AX2000 Function	Pin Number
VCCA	U11
VCCA	U20
VCCA	V11
VCCA	V20
VCCA	W11
VCCA	W20
VCCA	Y12
VCCA	Y13
VCCA	Y14
VCCA	Y15
VCCA	Y16
VCCA	Y17
VCCA	Y18
VCCA	Y19
VCCDA	AD24
VCCDA	AD7
VCCDA	AE15
VCCDA	AE16
VCCDA	AF12
VCCDA	AF13
VCCDA	AF15
VCCDA	AF18
VCCDA	AF19
VCCDA	AH27
VCCDA	AH4
VCCDA	C13
VCCDA	C27
VCCDA	C5
VCCDA	D13
VCCDA	D19
VCCDA	D3
VCCDA	E18
VCCDA	F15
VCCDA	F16
VCCDA	F26

FG896	
AX2000 Function	Pin Number
VCCDA	G16
VCCDA	T25
VCCDA	T4
VCCIB0	A3
VCCIB0	B3
VCCIB0	J10
VCCIB0	J11
VCCIB0	J12
VCCIB0	K11
VCCIB0	K12
VCCIB0	K13
VCCIB0	K14
VCCIB0	K15
VCCIB1	A28
VCCIB1	B28
VCCIB1	J19
VCCIB1	J20
VCCIB1	J21
VCCIB1	K16
VCCIB1	K17
VCCIB1	K18
VCCIB1	K19
VCCIB1	K20
VCCIB2	C29
VCCIB2	C30
VCCIB2	K22
VCCIB2	L21
VCCIB2	L22
VCCIB2	M21
VCCIB2	M22
VCCIB2	N21
VCCIB2	P21
VCCIB2	R21
VCCIB3	AA22
VCCIB3	AH29

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

FG1152	
AX2000 Function	Pin Number
IO311NB7F29	N3
IO311PB7F29	P3
IO312NB7F29	P7
IO312PB7F29	R7
IO313NB7F29	P6
IO313PB7F29	R6
IO314NB7F29	M2
IO314PB7F29	N2
IO315NB7F29	N4
IO315PB7F29	P4
IO316NB7F29	R9
IO316PB7F29	R8
IO317NB7F29	N5
IO317PB7F29	P5
IO318NB7F29	R10
IO318PB7F29	R11
IO319NB7F29	L2
IO319PB7F29	L1
IO320NB7F29	N8
IO320PB7F29	P8
IO321NB7F30	M6
IO321PB7F30	N6
IO322NB7F30	P10
IO322PB7F30	P9
IO323NB7F30	L3
IO323PB7F30	M3
IO324NB7F30	M7
IO324PB7F30	N7
IO325NB7F30	K2
IO325PB7F30	K1
IO326NB7F30	G2
IO326PB7F30	H2
IO327NB7F30	L6
IO327PB7F30	L5
IO328NB7F30	N10

FG1152	
AX2000 Function	Pin Number
IO328PB7F30	N9
IO329NB7F30	J4
IO329PB7F30	K4
IO330NB7F30	J5
IO330PB7F30	K5
IO331NB7F30	M10
IO331PB7F30	M9
IO332NB7F31	L8
IO332PB7F31	M8
IO333NB7F31	F2
IO333PB7F31	F1
IO334NB7F31	J6
IO334PB7F31	K6
IO335NB7F31	H4
IO335PB7F31	H3
IO336NB7F31	K7
IO336PB7F31	L7
IO337NB7F31	G4
IO337PB7F31	G3
IO338NB7F31	K9
IO338PB7F31	L9
IO339NB7F31	H6
IO339PB7F31	H5
IO340NB7F31	H7
IO340PB7F31	J7
IO341NB7F31	J8
IO341PB7F31	K8
Dedicated I/O	
GND	A13
GND	A2
GND	A22
GND	A27
GND	A3
GND	A31
GND	A32

FG1152	
AX2000 Function	Pin Number
GND	A33
GND	A4
GND	A8
GND	AA14
GND	AA15
GND	AA16
GND	AA17
GND	AA18
GND	AA19
GND	AA20
GND	AA21
GND	AB1
GND	AB13
GND	AB22
GND	AB34
GND	AC12
GND	AC23
GND	AC30
GND	AC5
GND	AD11
GND	AD24
GND	AD31
GND	AD4
GND	AE3
GND	AE32
GND	AF2
GND	AF33
GND	AG1
GND	AG27
GND	AG34
GND	AG8
GND	AH28
GND	AH7
GND	AJ29
GND	AJ6

CQ352	
AX500 Function	Pin Number
VCCDA	346
VCCIB0	321
VCCIB0	333
VCCIB0	344
VCCIB1	273
VCCIB1	285
VCCIB1	297
VCCIB2	227
VCCIB2	239
VCCIB2	245
VCCIB2	257
VCCIB3	185
VCCIB3	197
VCCIB3	203
VCCIB3	215
VCCIB4	144
VCCIB4	156
VCCIB4	168
VCCIB5	96
VCCIB5	108
VCCIB5	120
VCCIB6	50
VCCIB6	62
VCCIB6	68
VCCIB6	80
VCCIB7	8
VCCIB7	20
VCCIB7	26
VCCIB7	38
VCCPLA	317
VCCPLB	315
VCCPLC	303
VCCPLD	301
VCCPLE	140
VCCPLF	138

CQ352	
AX500 Function	Pin Number
VCCPLG	126
VCCPLH	124
VCOMPLA	318
VCOMPLB	316
VCOMPLC	304
VCOMPLD	302
VCOMPLE	141
VCOMPLF	139
VCOMPLG	127
VCOMPLH	125
VPUMP	267

CQ352	
AX1000 Function	Pin Number
IO131PB4F12	171
IO132NB4F12	166
IO132PB4F12	167
IO133NB4F12	164
IO133PB4F12	165
IO134NB4F12	160
IO134PB4F12	161
IO136NB4F12	158
IO136PB4F12	159
IO137NB4F12	154
IO137PB4F12	155
IO138NB4F12	152
IO138PB4F12	153
IO153NB4F14	146
IO153PB4F14	147
IO159NB4F14/CLKEN	142
IO159PB4F14/CLKEP	143
IO160NB4F14/CLKFN	136
IO160PB4F14/CLKFP	137
Bank 5	
IO161NB5F15/CLKGN	128
IO161PB5F15/CLKGP	129
IO162NB5F15/CLKHN	122
IO162PB5F15/CLKHP	123
IO167NB5F15	118
IO167PB5F15	119
IO183NB5F17	110
IO183PB5F17	111
IO184NB5F17	112
IO184PB5F17	113
IO185NB5F17	104
IO185PB5F17	105
IO186NB5F17	106
IO186PB5F17	107
IO187NB5F17	98

CQ352	
AX1000 Function	Pin Number
IO187PB5F17	99
IO188NB5F17	100
IO188PB5F17	101
IO190NB5F17	94
IO190PB5F17	95
IO192NB5F17	92
IO192PB5F17	93
Bank 6	
IO193PB6F18	86
IO194NB6F18	84
IO194PB6F18	85
IO196NB6F18	78
IO196PB6F18	79
IO197NB6F18	82
IO197PB6F18	83
IO198NB6F18	76
IO198PB6F18	77
IO203NB6F19	72
IO203PB6F19	73
IO204NB6F19	70
IO204PB6F19	71
IO205NB6F19	66
IO205PB6F19	67
IO206NB6F19	64
IO206PB6F19	65
IO207NB6F19	60
IO207PB6F19	61
IO208NB6F19	58
IO208PB6F19	59
IO211NB6F19	54
IO211PB6F19	55
IO212NB6F19	52
IO212PB6F19	53
IO223NB6F20	48
IO223PB6F20	49

CQ352	
AX1000 Function	Pin Number
IO224NB6F20	46
IO224PB6F20	47
Bank 7	
IO225NB7F21	40
IO225PB7F21	41
IO226NB7F21	42
IO226PB7F21	43
IO237NB7F22	34
IO237PB7F22	35
IO238NB7F22	36
IO238PB7F22	37
IO240NB7F22	30
IO240PB7F22	31
IO241NB7F22	28
IO241PB7F22	29
IO242NB7F22	24
IO242PB7F22	25
IO244NB7F22	22
IO244PB7F22	23
IO245NB7F22	18
IO245PB7F22	19
IO246NB7F22	16
IO246PB7F22	17
IO249NB7F23	12
IO249PB7F23	13
IO250NB7F23	10
IO250PB7F23	11
IO256NB7F23	4
IO256PB7F23	5
IO257NB7F23	6
IO257PB7F23	7
Dedicated I/O	
GND	1
GND	9
GND	15